

Appl. No. 10/707,718
Amdt. dated April 27, 2006
Reply to Office action of February 08, 2006

AMENDMENTS TO THE CLAIMS

1. (Original) A computer system comprising:
a housing;
5 a motherboard installed inside the housing, the motherboard comprising:
a top surface;
a bottom surface; and
a central processing unit installed on the bottom surface for processing data;
a cage installed on a region inside of the housing and adjacent to the top surface of
10 the motherboard; and
at least an integrated drive electronics device installed inside the cage.
2. (Original) The computer system of claim 1 further comprising a first heat-ventilating
device installed on a region inside of the housing and adjacent to the bottom surface
15 of the motherboard for ventilating heat generated by the central processing unit to a
region outside of the housing.
3. (Original) The computer system of claim 1, wherein the first heat-ventilating device
is a pipeline cooler.
20
4. (Original) The computer system of claim 2 further comprising at least a first
heat-ventilating hole installed on the housing and adjacent to the bottom surface of
the motherboard, the first heat-ventilating device ventilating heat generated by the
central processing unit through the first heat-ventilating hole and to a region outside
25 of the housing.
5. (Original) The computer system of claim 1 further comprising a second
heat-ventilating device installed on a region inside of the housing and adjacent to the

Appl. No. 10/707,718
Amdt. dated April 27, 2006
Reply to Office action of February 08, 2006

top surface of the motherboard for ventilating heat generated by the integrated drive electronics device to a region outside of the housing.

- 5 6. (Original) The computer system of claim 5, wherein the second heat-ventilating device is a fan cooler.
- 10 7. (Original) The computer system of claim 5 further comprising at least a second heat-ventilating hole installed on the housing and adjacent to the top surface of the motherboard, the second heat-ventilating device ventilating heat generated by the integrated drive electronics device through the second heat-ventilating hole and to a region outside of the housing.
- 15 8. (Original) The computer system of claim 1 further comprising at least a memory slot.
- 15 9. (Currently Amended) The computer system of claim 8, wherein the memory slot is ~~obliquely~~ installed on the bottom surface of the motherboard obliquely with respect to the bottom surface of the motherboard.
- 20 10. (Original) The computer system of claim 9, wherein the obliquely installed memory slot has a height smaller than that of the central processing unit.
11. (Original) The computer system of claim 1 further comprising a motherboard cage installed on top of the top surface of the motherboard and beneath the cage.
- 25 12. (Original) The computer system of claim 11, wherein the motherboard cage comprises at least a positioning aperture and the cage comprises at least a positioning device corresponding to the positioning aperture for plugging into the positioning aperture when the cage is mounted on the motherboard cage.

Appl. No. 10/707,718
Amdt. dated April 27, 2006
Reply to Office action of February 08, 2006

13. (Currently Amended) The computer system of claim 11, wherein the motherboard cage comprises a plurality of ~~connectors~~ headers.
- 5 14. (Original) The computer system of claim 1, wherein the integrated drive electronics device is a hard disk drive.
15. (Original) The computer system of claim 1, wherein the integrated drive electronics device is a card reader.
- 10 16. (Original) The computer system of claim 1, wherein the integrated drive electronics device is a CD-ROM drive.
- 15 17. (Original) The computer system of claim 1, wherein the integrated drive electronics device is a floppy disk drive.
18. (Original) The computer system of claim 1, wherein the cage comprises a plurality of connectors.